

BRAD76225SA



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Note 1: If the device operating conditions over the maximum rating of the above-mentioned conditions, may cause permanent damage to the device. The above parameters is only part of the operating conditions the maximum, we do not recommend the device running outside the scope of this specification. If the device to work long hours under the condition of absolute maximum limit, its stability may be affected.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Supply Voltage Section(V_{DD} Pin)						
Start-up current into VDD pin	I _{VDD_st}	V _{DD_ON} -1 V		3	20	uA
Operation Current	I _{VDD_op}			0.8		mA

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Rev.B May.-2019



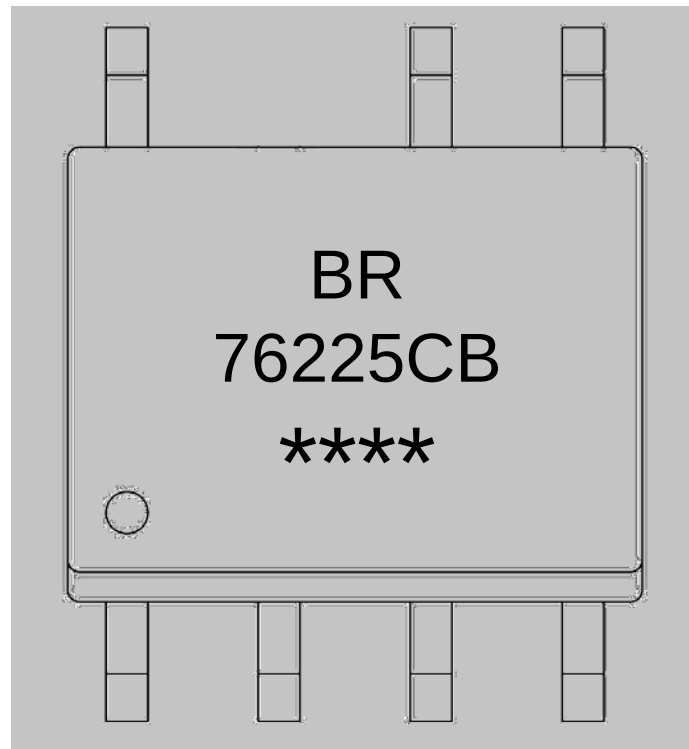
DATA SHEET

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Cable Drop Compensation (CDC) Current	$I_{\text{Cable_max}}$			45		μA
Current Sense Input Section (CS Pin)						
CS Input Leading Edge Blanking Time	T_{LEB}			350		ns
Minimum overcurrent protection threshold	$V_{\text{TH_OCPmin}}$			500		mV
Maximum overcurrent protection threshold	$V_{\text{TH_OCPmax}}$			550		mV

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Ø □ =) ¢ / **Package Dimensions**

/ Marking Instructions



BR

76225

C

B

BJT

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Note

BR

Company Code

76225

Product Type

C

Distinguishing output power corresponding to product series table, varies with product type suffix

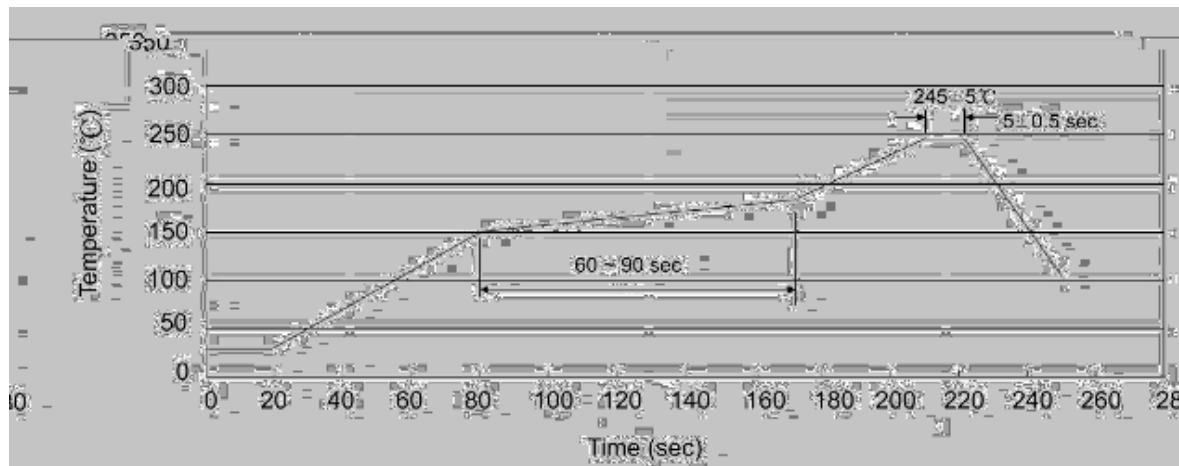
B

Distinguish internal power BJT, or default consistent with product model suffix

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Lot No.Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | |
|---|---------|-----------|---|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type